

In the Claims:

1. (Currently Amended) A system (1) comprising:
 - a first semiconductor device (2a), and
 - a second semiconductor device (2b),
 - wherein the first semiconductor device (2a) and the second semiconductor device each
comprise ~~comprises~~ a voltage supply device means (3a),
 - wherein ~~characterized in that~~ said voltage supply device means (3a) of said first
semiconductor device (2a) is connected to said second semiconductor device (2b), so that said
voltage supply device means (3a) of said first semiconductor device (2a) can provide a supply
voltage for said second semiconductor device (2b). and
 - wherein the system is adapted such that, in a first operating mode of the second
semiconductor device, the voltage supply device of said second semiconductor device provides
the supply voltage for the second semiconductor device, and, in a second operating mode of the
second semiconductor device, the voltage supply device of said first semiconductor device
provides the supply voltage for the second semiconductor device.
2. (Currently Amended) The system (1) according to claim 1, wherein said first
semiconductor device (2a) and said second semiconductor device (2b) are arranged in ~~the~~ a same
housing (4).
3. (Currently Amended) The system (1) according to claim 2, wherein said first and second
semiconductor devices (2a, 2b) are arranged in said housing (4) in a stacked manner.
4. (Currently Amended) The system (1) according to claim 2, wherein said housing (4) is a
plug mountable semiconductor device housing.
5. (Currently Amended) The system (1) according to claim 4, wherein said plug mountable
semiconductor device housing is a Dual-In-Line (DIL) housing.

6. (Currently Amended) The system (1) according to claim 4, wherein said plug mountable semiconductor device housing is a Pin-Grid-Array (PGA) housing.
7. (Currently Amended) The system (1) according to claim 2, wherein said housing (4) is a surface mountable semiconductor device housing.
8. (Currently Amended) The system (1) according to claim 1, said system comprising one or several further semiconductor devices.
9. (Currently Amended) The system (1) according to claim 8, wherein said one or said several further semiconductor device(s) is/are arranged in the same housing (4), in particular in the same semiconductor device housing as as ~~as are~~ said first and said second semiconductor devices (2a, 2b).
10. (Currently Amended) The system according to claim 8, wherein said voltage supply device means (3a) of said first semiconductor device (2a) is additionally also connected to said one or to said several further semiconductor device(s), so that said voltage supply device means (3a) of said first semiconductor device (2a) can additionally provide a supply voltage for said one or said several further semiconductor device(s).
11. (Currently Amended) The system (1) according to ~~any of~~ claim 8, wherein said first semiconductor device (2a) comprises a further voltage supply device means that is connected to said one or said several further semiconductor device(s), so that said further voltage supply device means of said first semiconductor device (2a) can provide a supply voltage for said one or said several further semiconductor device(s).
12. (Currently Amended) The system (1) according to claim 1, wherein said first and/or said second semiconductor devices (2a, 2b), and/or said one and/or said several further semiconductor devices are memory devices.

13. (Currently Amended) The system (1) according to claim 12, wherein said memory device is a table memory device or said memory devices (2a, 2b) are table memory devices, respectively.

14. (Currently Amended) The system (1) according to claim 13, wherein ~~said table memory device is a RAM table memory device~~ or said table memory device or said table memory devices are RAM table memory devices, respectively.

15. (Currently Amended) The system (1) according to claim 14, wherein said RAM table memory device is a DRAM table memory device or said RAM table memory devices are DRAM table memory devices, respectively.

16. (Currently Amended) The system (1) according to claim 13, wherein said table memory device is a ROM table memory device or said table memory devices are ROM table memory devices, respectively.

17. (Currently Amended) The system (1) according to claim 12, wherein said memory device is ~~a functional memory device~~ or said memory devices are ~~fundamental memory devices, respectively, in particular~~ programmable logic devices (PLDs) and/or programmable logic arrays (PLAs). ~~PLDs and/or PLAs.~~

18. (Currently Amended) The system (1) according to claim 1, wherein said voltage supply device means (3a) and/or said further voltage supply device means provide a voltage supply for said first semiconductor device (2a).

19. (Currently Amended) The system (1) according to claim 1, wherein said voltage supply means (3a) and/or said further voltage supply means generate(s) the respective supply voltage from an external voltage.

20. (Currently Amended) The system (1) according to claim 1, wherein said voltage supply ~~device means (3a)~~ and/or said further voltage supply ~~device means~~ are or comprise a voltage regulating ~~device means~~.

21. (Currently Amended) The system (1) according to claim 1, wherein said voltage supply ~~device means (3a)~~ and/or said further voltage supply ~~device means~~ are or comprise a charge pump.

22. (Cancelled)

23. (Currently Amended) The system (1) according to claim 1 22, wherein said voltage supply ~~device means (3b)~~ of said second semiconductor device (2b) is activated in the first operating mode, and wherein said supply voltage ~~device means (3b)~~ of said second semiconductor device (2b) is deactivated in the second operating mode.

24. (Currently Amended) The system (1) according to claim 1 22, wherein the second operating mode is a standby mode.

25. (Currently Amended) The system (1) according to ~~claims~~ claim 1 22, wherein the second operating mode is a refresh mode.

26. (Currently Amended) The system (1) according to claim 1 22, wherein the first operating mode is a working mode, in particular a mode in which external access to the second semiconductor device (2b) is performed.

27. (Currently Amended) The system (1) according to claim 1, wherein ~~a device function adjusting means, in particular~~ an appropriate fuse[[,]] is provided on said first and/or second semiconductor device(s) (2a, 2b), by means of which it is determined whether the corresponding semiconductor device (2a, 2b) is to assume the function of said first semiconductor device (2a) or the function of said second semiconductor device (2b).

28. (Currently Amended) The system (1) according to claim 1, wherein said voltage supply device means (3b) of said first semiconductor device (2a) is connected to a corresponding pad (5a) of said first semiconductor device (2a).

29. (Currently Amended) The system (1) according to claim 28, wherein said pad (5a) of said first semiconductor device (2a) is connected to a corresponding pad (5b) of said second semiconductor device (2b), in particular to a pad (5b) which said voltage supply device means (3b) of said second semiconductor device (2b) can be connected to.

30. (Currently Amended) The system (1) according to claim 29, wherein said pad (5a) of said first semiconductor device (2a) is connected directly to the corresponding pad (5b) of said second semiconductor device (2b), in particular by means of an appropriate bonding wire (6).

31. (Currently Amended) The system (1) according to claim 29, wherein said pad (5a) of said first semiconductor device (2a) is connected indirectly to the corresponding pad (5b) of said second semiconductor device (2b), in particular via an interposer (9).

32. (New) The system according to claim 12, wherein said memory devices are functional memory devices.

33. (New) The system according to claim 12, wherein said memory devices are fundamental memory devices.